

NOTES:

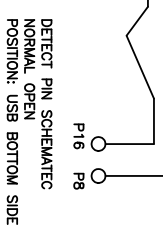
1. MATERIAL:
HOUSING:THERMOPLASTIC, HIGH TEMP, 30% G/F UL94 V-0
COLOR:BLACK
SPACER:THERMOPLASTIC, HIGH TEMP, 30% G/F UL94 V-0
COLOR:BLACK
FRONT SHELL: COPPER ALLOY
GROUNDING STRIP: STEEL
ESATA CONTACT: COPPER ALLOY
USB CONTACT: COPPER ALLOY
DETECT PIN: COPPER ALLOY
LATCH: STEEL
2. FINISH:
CONTACT: GOLD PLATING ON CONTACT AREA
2.54um[100u"] MIN. MATT TIN PLATING ON SOLDER TAILS
1.27um[50u"] MIN. NICKEL UNDERPLATING OVER ALL
FRONT SHELL: 2.54um[100u"] MIN. NICKEL UNDERPLATING OVER ALL
DETECT PIN:
2.54um[100u"] MIN. MATT TIN PLATING OVER ALL.
1.27um[50u"] MIN. NICKEL UNDERPLATING OVER ALL

3. THE HOUSING WILL WITHSTAND EXPOSURE TO 260 C. TEMP. FOR 10 SECOND IN A WAVE SOLDER APPLICATION WITH A 1.6MM MIN. THICK CIRCUIT BOARD.

4. PRODUCT GS-12-402
PACKING SPEC: GS-14-1099
5. NUMBERING INFORMATION
10081268 - 0 0 X X L F
LEAD FREE
BLANK: TRAY PACKING
R : TAPE & REEL PACKING
1 - 15u" GOLD PLATING
3 - 30u" GOLD PLATING

PIN DEFINITION

USB TOP	NAME	TYPE	ESATA	NAME	TYPE
P1	VBUS	P9	GND	P9	GND
P2	D-	P10	A+	P10	A+
P3	D+	P11	A-	P11	A-
P4	GND	P12	GND	P12	GND
		P13	B-	P13	B-
		P14	B+	P14	B+
		P15	GND	P15	GND



REFERENCE P.C.BOARD LAYOUT T=1.60mm
PCB TOLERANCE: ±0.05

USB TOP	NAME	TYPE	ESATA	NAME	TYPE
P1	VBUS	P9	GND	P9	GND
P2	D-	P10	A+	P10	A+
P3	D+	P11	A-	P11	A-
P4	GND	P12	GND	P12	GND
		P13	B-	P13	B-
		P14	B+	P14	B+
		P15	GND	P15	GND

mat'l. code	ecn no.	dr	date	linear	tolerances unless otherwise specified	CUSTOMER COPY	title	product family	code
A	108-1081	S.Lin	04/28/08	.XXX ± 0.25	X ± 0.38	projection	USB 4P OVER I/O STORAGE 7P 2 IN 1	SATA	TWN
B	108-1125	S.Lin	06/20/08	.XXX ± 0.15		MM	USB 4P, R/A, RVS, DIP, OFFSET TYPE.		sheet
C	108-1144	S.Lin	07/25/08	angles	0° ± 2°	scale			1 of 1
D	108-1166	S.Lin	09/17/08	engr		NA			
				chr					
				engr					
				chr					
				engr					
				chr					

ACAD

3

code code

4

3

4